

Electronic Patent Application Fee Transmittal				
Application Number:		10591455		
Filing Date:		18-Jan-2007		
Title of Invention:		THERMOPLASTIC RESIN COMPOSITION AND MOLDED ARTICLE COMPRISING THE SAME		
First Named Inventor/Applicant Name:		Hideo Aoki		
Filer:		Marvin Jay Spivak/Mimi Chanthaphone		
Attorney Docket Number:		295958US0PCT		
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Printed copy of patent - no color	8001	2	3	6
Total in USD (\$)				1816